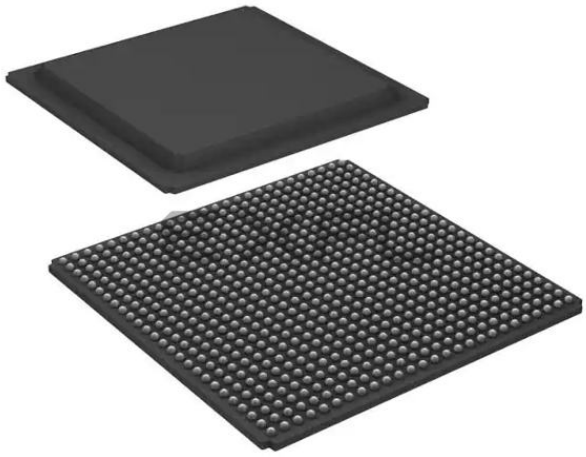

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	4848
Number of Logic Elements/Cells	43632
Total RAM Bits	3538944
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp40-7fg676c

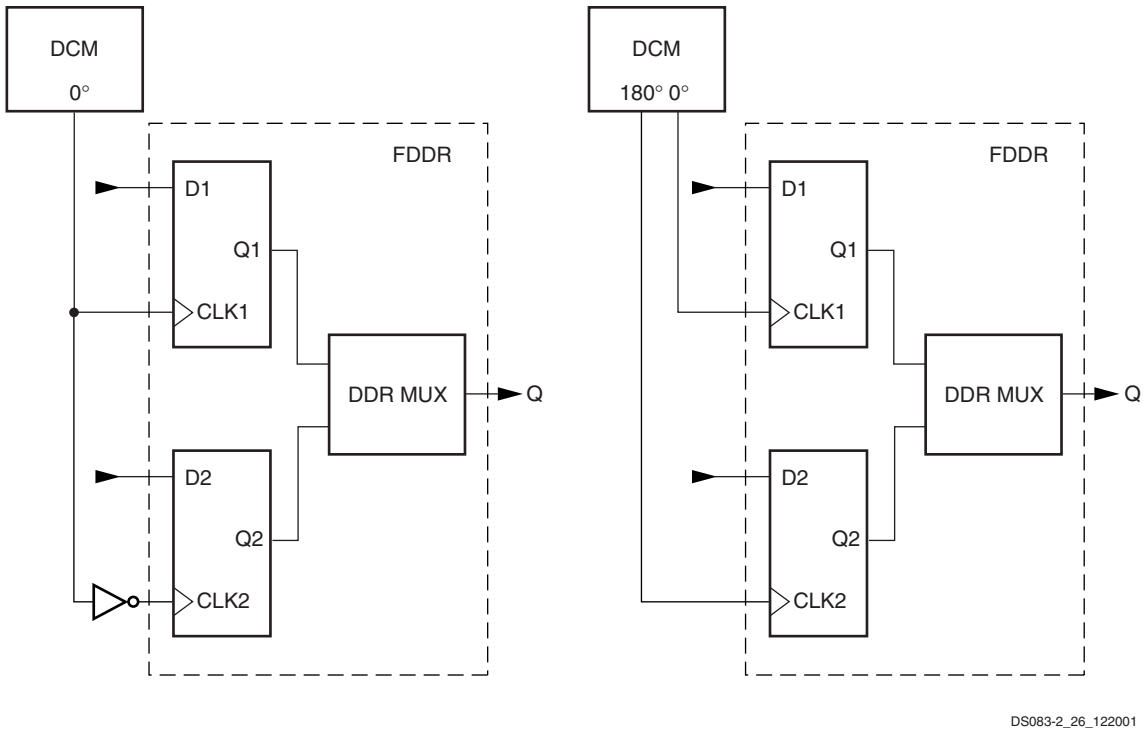


Figure 20: **Double Data Rate Registers**

This DDR mechanism can be used to mirror a copy of the clock on the output. This is useful for propagating a clock along the data that has an identical delay. It is also useful for multiple clock generation, where there is a unique clock driver for every clock load. Virtex-II Pro devices can produce many copies of a clock with very little skew.

Each group of two registers has a clock enable signal (ICE for the input registers, OCE for the output registers, and TCE for the 3-state registers). The clock enable signals are active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

Each IOB block has common synchronous or asynchronous set and reset (SR and REV signals). Two neighboring IOBs have a shared routing resource connecting the ICLK and OTCLK pins on pairs of IOBs. If two adjacent IOBs using DDR registers do not share the same clock signals on their clock pins (ICLK1, ICLK2, OTCLK1, and OTCLK2), one of the clock signals will be unroutable.

The IOB pairing is identical to the LVDS IOB pairs. Hence, the package pin-out table can also be used for pin assignment to avoid conflict.

SR forces the storage element into the state specified by the SRHIGH or SRLOW attribute. SRHIGH forces a logic 1. SRLOW forces a logic “0”. When SR is used, a second input (REV) forces the storage element into the opposite state. The reset condition predominates over the set condition. The initial state after configuration or global initialization state is defined by a separate INIT0 and INIT1 attribute. By default, the SRLOW attribute forces INIT0, and the SRHIGH attribute forces INIT1.

For each storage element, the SRHIGH, SRLOW, INIT0, and INIT1 attributes are independent. Synchronous or asynchronous set / reset is consistent in an IOB block.

All the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Each register or latch, independent of all other registers or latches, can be configured as follows:

- No set or reset
- Synchronous set
- Synchronous reset
- Synchronous set and reset
- Asynchronous set (preset)
- Asynchronous reset (clear)
- Asynchronous set and reset (preset and clear)

The synchronous reset overrides a set, and an asynchronous clear overrides a preset.

Refer to Figure 21.

Table 24: **RocketIO X Receiver Switching Characteristics**(1)

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance using default equalization and PRBS-15 pattern	T_{JTOL}	2.488 Gb/s		0.80	0.65	UI(2)
		3.125 Gb/s		0.80	0.65	UI
		4.25 Gb/s		0.80	0.65	UI
		6.25 Gb/s		0.80	0.65	UI
Receive random jitter tolerance	T_{RJTOL}	2.488 Gb/s		0.30		UI
		3.125 Gb/s		0.30		UI
		4.25 Gb/s		0.30		UI
		6.25 Gb/s		0.30		UI
Receive sinusoidal jitter tolerance measured at 70 MHz	T_{SJTOL}	2.488 Gb/s		0.30	0.15	UI
		3.125 Gb/s		0.30	0.15	UI
		4.25 Gb/s		0.30	0.15	UI
		6.25 Gb/s		0.30	0.15	UI
Receive deterministic jitter tolerance	T_{DJTOL}	2.488 Gb/s		0.55	0.45	UI
		3.125 Gb/s		0.55	0.45	UI
		4.25 Gb/s		0.55	0.45	UI
		6.25 Gb/s		0.50	0.45	UI
Receive latency(3)	T_{RXLAT}			25	34(4)	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%
Differential receive input sensitivity	V_{EYE}			120	250	mV

Notes:
1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Receive latency delay RXP/RXN to RXDATA. Refer to ***RocketIO X Transceiver User Guide*** for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

IOB Input Switching Characteristics Standard Adjustments

Table 36 gives all standard-specific data input delay adjustments.

Table 36: **IOB Input Switching Characteristics Standard Adjustments**

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL	T_{ILVTTL}	0.07	0.08	0.09	ns
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	$T_{ILVCMOS33}$	0.04	0.05	0.05	ns
LVCMOS, 2.5V	LVCMOS25	$T_{ILVCMOS25}$	0.00	0.00	0.00	ns
LVCMOS, 1.8V	LVCMOS18	$T_{ILVCMOS18}$	0.29	0.33	0.36	ns
LVCMOS, 1.5V	LVCMOS15	$T_{ILVCMOS15}$	0.36	0.41	0.45	ns
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	T_{ILVDS_25}	0.31	0.36	0.40	ns
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$T_{ILVDSEXT\_25}$	0.33	0.37	0.41	ns
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	T_{IULVDS_25}	0.31	0.36	0.40	ns
BLVDS (Bus LVDS), 2.5V	BLVDS_25	T_{IBLVDS_25}	0.00	0.00	0.00	ns
LDT (HyperTransport), 2.5V	LDT_25	T_{ILDT_25}	0.31	0.36	0.40	ns
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	$T_{ILVPECL\_25}$	0.69	0.80	0.88	ns
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	T_{IPCI33_3}	0.14	0.16	0.18	ns
PCI, 66 MHz, 3.3V	PCI66_3	T_{IPCI66_3}	0.15	0.17	0.19	ns
PCI-X, 133 MHz, 3.3V	PCIX	T_{IPCIX}	0.12	0.13	0.15	ns
GTL (Gunning Transceiver Logic)	GTL	T_{IGTL}	0.59	0.68	0.74	ns
GTL Plus	GTLP	T_{IGTLP}	0.63	0.72	0.79	ns
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	T_{IHSTL_I}	0.59	0.68	0.75	ns
HSTL, Class II	HSTL_II	T_{IHSTL_II}	0.59	0.68	0.75	ns
HSTL, Class III	HSTL_III	T_{IHSTL_III}	0.57	0.66	0.72	ns
HSTL, Class IV	HSTL_IV	T_{IHSTL_IV}	0.58	0.67	0.74	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{IHSTL\_I\_18}$	0.57	0.65	0.72	ns
HSTL, Class II, 1.8V	HSTL_II_18	$T_{IHSTL\_II\_18}$	0.55	0.63	0.69	ns
HSTL, Class III, 1.8V	HSTL_III_18	$T_{IHSTL\_III\_18}$	0.56	0.64	0.70	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	$T_{IHSTL\_IV\_18}$	0.57	0.65	0.71	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	$T_{ISSTL18\_I}$	0.62	0.72	0.79	ns
SSTL, Class II, 1.8V	SSTL18_II	$T_{ISSTL18\_II}$	0.64	0.73	0.81	ns
SSTL, Class I, 2.5V	SSTL2_I	T_{ISSTL2_I}	0.62	0.72	0.79	ns
SSTL, Class II, 2.5V	SSTL2_II	T_{ISSTL2_II}	0.64	0.73	0.81	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T_{ILVDCI_33}	–0.05	–0.05	–0.06	ns
LVDCI, 2.5V	LVDCI_25	T_{ILVDCI_25}	0.00	0.00	0.00	ns
LVDCI, 1.8V	LVDCI_18	T_{ILVDCI_18}	0.07	0.09	0.09	ns
LVDCI, 1.5V	LVDCI_15	T_{ILVDCI_15}	0.13	0.15	0.17	ns
LVDCI, 2.5V, Half-Impedance	LVDCI_DV2_25	$T_{ILVDCI\_DV2\_25}$	0.00	0.00	0.00	ns
LVDCI, 1.8V, Half-Impedance	LVDCI_DV2_18	$T_{ILVDCI\_DV2\_18}$	0.07	0.09	0.09	ns
LVDCI, 1.5V, Half-Impedance	LVDCI_DV2_15	$T_{ILVDCI\_DV2\_15}$	0.13	0.15	0.17	ns
HSLVDCI (High-Speed Low-Voltage DCI), 1.5V	HSLVDCI_15	$T_{IHSLVDCI\_15}$	0.59	0.68	0.75	ns

Output Delay Measurements

Output delays are measured using a Tektronix P6245 TDS500/600 probe (< 1 pF) across approximately 4" of FR4 microstrip trace. Standard termination was used for all testing. (See ***Virtex-II Pro Platform FPGA User Guide*** for details.) The propagation delay of the 4" trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setup shown in Figure 6.

Measurements and test conditions are reflected in the IBIS models except where the IBIS format precludes it. (IBIS models can be found on the web at **http://support.xilinx.com/support/sw_ibis.htm**.) Parameters V_{REF}, R_{REF}, C_{REF}, and V_{MEAS} fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using the following method:

1. Simulate the output driver of choice into the generalized test setup, using values from Table 40.
2. Record the time to V_{MEAS}.
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to V_{MEAS}.
5. Compare the results of steps 2 and 4. The increase or decrease in delay should be added to or subtracted from the I/O Output Standard Adjustment value (Table 38) to yield the actual worst-case propagation delay (clock-to-input) of the PCB trace.

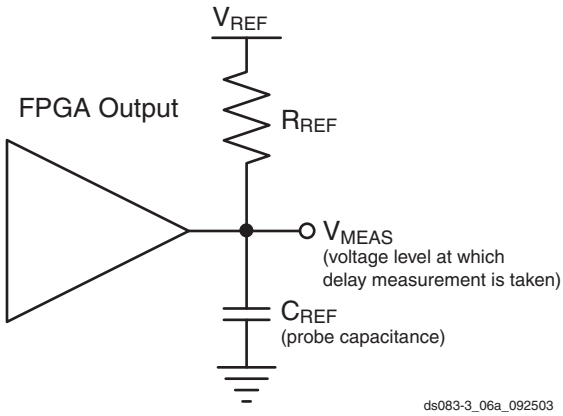


Figure 6: **Generalized Test Setup**

Table 40: **Output Delay Measurement Methodology**

Description	IOSTANDARD Attribute	R_{REF} (Ω)	C_{REF} (1) (pF)	V_{MEAS} (V)	V_{REF} (V)
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL (all)	1M	0	1.65	0
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	1M	0	1.65	0
LVCMOS, 2.5V	LVCMOS25	1M	0	1.25	0
LVCMOS, 1.8V	LVCMOS18	1M	0	0.9	0
LVCMOS, 1.5V	LVCMOS15	1M	0	0.75	0
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3 (rising edge)	25	10 (2)	0.94	0
	PCI33_3 (falling edge)	25	10 (2)	2.03	3.3
PCI, 66 MHz, 3.3V	PCI66_3 (rising edge)	25	10 (2)	0.94	0
	PCI66_3 (falling edge)	25	10 (2)	2.03	3.3
PCI-X, 133 MHz, 3.3V	PCIX (rising edge)	25	10 (3)	0.94	0
	PCIX (falling edge	25	10 (3)	2.03	3.3
GTL (Gunning Transceiver Logic)	GTL	25	0	0.8	1.2
GTL Plus	GTLP	25	0	1.0	1.5
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	50	0	V_{REF}	0.75
HSTL, Class II	HSTL_II	25	0	V_{REF}	0.75
HSTL, Class III	HSTL_III	50	0	0.9	1.5
HSTL, Class IV	HSTL_IV	25	0	0.9	1.5
HSTL, Class I, 1.8V	HSTL_I_18	50	0	V_{REF}	0.9
HSTL, Class II, 1.8V	HSTL_II_18	25	0	V_{REF}	0.9
HSTL, Class III, 1.8V	HSTL_III_18	50	0	1.1	1.8
HSTL, Class IV, 1.8V	HSTL_IV_18	25	0	1.1	1.8

Virtex-II Pro Receiver Data-Valid Window (R_X)

R_X is the required minimum aggregate valid data period for a source-synchronous data bus at the pins of the device and is calculated as follows:

$$R_X = [TSAMP^{(1)} + TCKSKEW^{(2)} + TPKGSKEW^{(3)}]$$

Notes:

1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
   - CLK0 and CLK180 DCM jitter in a quiet system
   - Worst-case duty-cycle distortion
   - DCM accuracy (phase offset)
   - DCM phase shift resolution.

   These measurements do not include package or clock tree skew.
2. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.
3. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/17/02	2.0	• Added new Virtex-II Pro family members. • Added timing parameters from speedsfile **v1.62**. • Added Table 46, Pipelined Multiplier Switching Characteristics. • Added 3.3V-vs-2.5V table entries for some parameters.
09/03/02	2.1	• Added Source-Synchronous Switching Characteristics section. • Added absolute max ratings for 3.3V-vs-2.5V parameters in Table 1. • Added recommended operating conditions for V_{IN} and RocketIO footnote to Table 2. • Updated SSTL2 values in Table 6. Added SSTL18 values: Table 6, Table 39, Table 32. [Table 32 removed in v2.8.] • Added Table 10, which contains LVPECL DC specifications.
09/27/02	2.2	Added section General Power Supply Requirements.
11/20/02	2.3	Updated parametric information in: • Table 1: Increase Absolute Max Rating for V_{CCO}, V_{REF}, V_{IN}, and V_{TS} from 3.6V to 3.75V. Delete cautionary footnotes related to voltage overshoot/undershoot. • Table 2: Delete V_{CCO} specifications for 2.5V and below operation. Delete footnote referencing special information for 3.3V operation. Add footnote for PCI/PCI-X. • Table 3: Add I_{BATT}. Delete I_L specifications for 2.5V and below operation. • Table 4: Add Typical Quiescent Supply Currents for XC2VP4 and XC2VP7 only • Table 6: Correct I_{OL} and I_{OH} for SSTL2 I. Add rows for LVTTL, LVCMOS33, and PCI-X. Correct max V_{IH} from V_{CCO} to 3.6V. • Table 7: Correct Min/Max V_{OD}, V_{OCM}, and V_{ICM} • Table 10: Reformat LVPECL DC Specifications to match Virtex-II data sheet format • Table 12: Correct parameter name from Differential Output Voltage to Single-Ended Output Voltage Swing. • Table 16: Add CPMC405CLOCK max frequencies • Table 27: Add footnote regarding serial data rate limitation in -5 part. • Table 39: Add rows for LVTTL, LVCMOS33, and PCI-X. • Table 32: Add LVTTL, LVCMOS33, and PCI-X. Correct all capacitive load values (except PCI/PCI-X) to 0 pF. [Table 32 removed in v2.8.] • Table 51: Correct CCLK max frequencies
11/25/02	2.4	Table 1: Correct lower limit of voltage range of V_{IN} and V_{TS} from –0.3V to –0.5V for 3.3V.

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
1	VCCO_1		K13			
1	VCCO_1		K12			
1	VCCO_1		K11			
1	VCCO_1		K10			
1	VCCO_1		J13			
1	VCCO_1		J12			
1	VCCO_1		J11			
1	VCCO_1		J10			
2	VCCO_2		R10			
2	VCCO_2		P10			
2	VCCO_2		N10			
2	VCCO_2		N9			
2	VCCO_2		M10			
2	VCCO_2		M9			
2	VCCO_2		L10			
2	VCCO_2		L9			
2	VCCO_2		K9			
2	VCCO_2		J9			
3	VCCO_3		AB9			
3	VCCO_3		AA9			
3	VCCO_3		Y10			
3	VCCO_3		Y9			
3	VCCO_3		W10			
3	VCCO_3		W9			
3	VCCO_3		V10			
3	VCCO_3		V9			
3	VCCO_3		U10			
3	VCCO_3		T10			
4	VCCO_4		AB13			
4	VCCO_4		AB12			
4	VCCO_4		AB11			
4	VCCO_4		AB10			
4	VCCO_4		AA15			
4	VCCO_4		AA14			
4	VCCO_4		AA13			
4	VCCO_4		AA12			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		C14			
N/A	GND		C3			
N/A	GND		B29			
N/A	GND		B2			
N/A	GND		A22			
N/A	GND		A9			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
5	IO_L44N_5	AK22				
5	IO_L44P_5	AJ22				
5	IO_L43N_5	AF21				
5	IO_L43P_5	AE21				
5	IO_L39N_5	AK24				
5	IO_L39P_5	AJ24				
5	IO_L38N_5	AH22				
5	IO_L38P_5	AG22				
5	IO_L37N_5	AF22				
5	IO_L37P_5	AE22				
5	IO_L27N_5/VREF_5	AL25	NC	NC		
5	IO_L27P_5	AK25	NC	NC		
5	IO_L26N_5	AJ23	NC	NC		
5	IO_L26P_5	AH23	NC	NC		
5	IO_L25N_5	AH24	NC	NC		
5	IO_L25P_5	AG24	NC	NC		
5	IO_L21N_5	AM26	NC	NC		
5	IO_L21P_5	AL26	NC	NC		
5	IO_L20N_5	AK26	NC	NC		
5	IO_L20P_5	AJ26	NC	NC		
5	IO_L19N_5	AF23	NC	NC		
5	IO_L19P_5	AE23	NC	NC		
5	IO_L09N_5/VREF_5	AL27				
5	IO_L09P_5	AK27				
5	IO_L08N_5	AH25				
5	IO_L08P_5	AG25				
5	IO_L07N_5/VREF_5	AF24				
5	IO_L07P_5	AE24				
5	IO_L06N_5/VRP_5	AM28				
5	IO_L06P_5/VRN_5	AL28				
5	IO_L05_5/No_Pair	AF25				
5	IO_L03N_5/D4	AK28				
5	IO_L03P_5/D5	AK29				
5	IO_L02N_5/D6	AH26				
5	IO_L02P_5/D7	AG26				
5	IO_L01N_5/RDWR_B	AL29				
5	IO_L01P_5/CS_B	AL30				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	VCCO_4	AD15				
4	VCCO_4	AJ10				
4	VCCO_4	AK15				
4	VCCO_4	AM6				
5	VCCO_5	AC18				
5	VCCO_5	AC19				
5	VCCO_5	AC20				
5	VCCO_5	AC21				
5	VCCO_5	AC22				
5	VCCO_5	AD20				
5	VCCO_5	AD21				
5	VCCO_5	AD22				
5	VCCO_5	AD23				
5	VCCO_5	AJ25				
5	VCCO_5	AK20				
5	VCCO_5	AM29				
6	VCCO_6	V23				
6	VCCO_6	W23				
6	VCCO_6	Y23				
6	VCCO_6	Y24				
6	VCCO_6	Y30				
6	VCCO_6	AA23				
6	VCCO_6	AA24				
6	VCCO_6	AB23				
6	VCCO_6	AB24				
6	VCCO_6	AC24				
6	VCCO_6	AE29				
6	VCCO_6	AJ32				
7	VCCO_7	F32				
7	VCCO_7	K29				
7	VCCO_7	M24				
7	VCCO_7	N23				
7	VCCO_7	N24				
7	VCCO_7	P23				
7	VCCO_7	P24				
7	VCCO_7	R23				
7	VCCO_7	R24				
7	VCCO_7	R30				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	TXPPAD17	AP12	NC	NC	NC	
N/A	TXNPAD17	AP13	NC	NC	NC	
N/A	VTTXPAD17	AN13	NC	NC	NC	
N/A	AVCCAUXTX17	AN12	NC	NC	NC	
N/A	AVCCAUXRX18	AN14				
N/A	VTRXPAD18	AN15				
N/A	RXNPAD18	AP14				
N/A	RXPPAD18	AP15				
N/A	GNDA18	AM15				
N/A	TXPPAD18	AP16				
N/A	TXNPAD18	AP17				
N/A	VTTXPAD18	AN17				
N/A	AVCCAUXTX18	AN16				
N/A	AVCCAUXRX19	AN18				
N/A	VTRXPAD19	AN19				
N/A	RXNPAD19	AP18				
N/A	RXPPAD19	AP19				
N/A	GNDA19	AM20				
N/A	TXPPAD19	AP20				
N/A	TXNPAD19	AP21				
N/A	VTTXPAD19	AN21				
N/A	AVCCAUXTX19	AN20				
N/A	AVCCAUXRX20	AN22	NC	NC	NC	
N/A	VTRXPAD20	AN23	NC	NC	NC	
N/A	RXNPAD20	AP22	NC	NC	NC	
N/A	RXPPAD20	AP23	NC	NC	NC	
N/A	GNDA20	AM23	NC	NC	NC	
N/A	TXPPAD20	AP24	NC	NC	NC	
N/A	TXNPAD20	AP25	NC	NC	NC	
N/A	VTTXPAD20	AN25	NC	NC	NC	
N/A	AVCCAUXTX20	AN24	NC	NC	NC	
N/A	AVCCAUXRX21	AN26				
N/A	VTRXPAD21	AN27				
N/A	RXNPAD21	AP26				
N/A	RXPPAD21	AP27				
N/A	GNDA21	AM27				
N/A	TXPPAD21	AP28				
N/A	TXNPAD21	AP29				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	GND	AF34				
N/A	GND	B34				
N/A	GND	C1				
N/A	GND	C2				
N/A	GND	C10				
N/A	GND	C16				
N/A	GND	C19				
N/A	GND	C25				
N/A	GND	C33				
N/A	GND	C34				
N/A	GND	D4				
N/A	GND	D31				
N/A	GND	E5				
N/A	GND	E12				
N/A	GND	E23				
N/A	GND	E30				
N/A	GND	F6				
N/A	GND	F29				
N/A	GND	G7				
N/A	GND	G28				
N/A	GND	B1				
N/A	GND	H8				
N/A	GND	H12				
N/A	GND	H15				
N/A	GND	H20				
N/A	GND	J1				
N/A	GND	H27				
N/A	GND	AF1				
N/A	GND	K3				
N/A	GND	K32				
N/A	GND	M5				
N/A	GND	M8				
N/A	GND	M27				
N/A	GND	M30				
N/A	GND	P14				
N/A	GND	P15				
N/A	GND	P16				

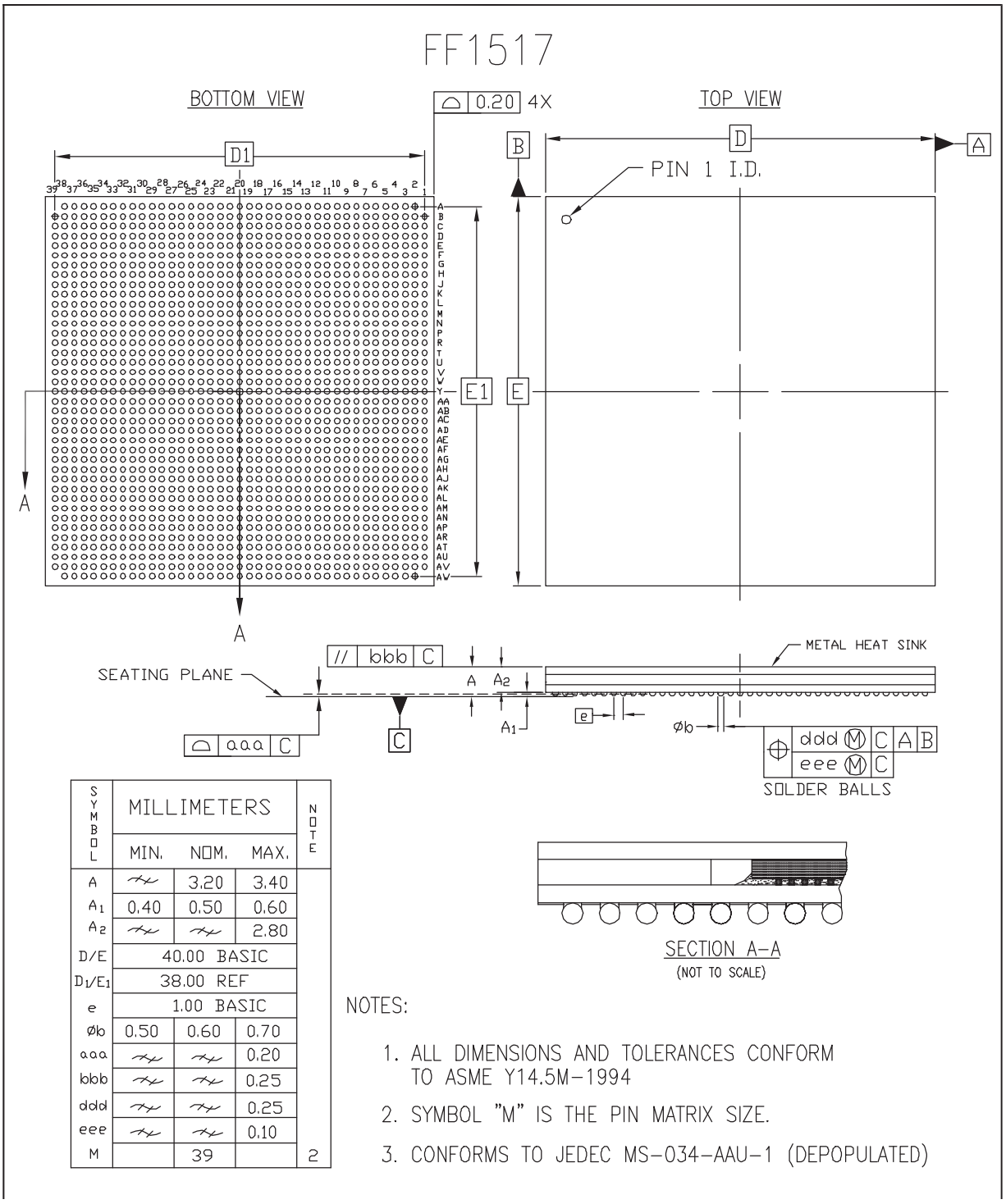
Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
4	IO_L38P_4	AH16		
4	IO_L39N_4	AR14		
4	IO_L39P_4	AP14		
4	IO_L43N_4	AU14		
4	IO_L43P_4	AT14		
4	IO_L44N_4	AH17		
4	IO_L44P_4	AG17		
4	IO_L45N_4	AN15		
4	IO_L45P_4/VREF_4	AM15		
4	IO_L46N_4	AR15		
4	IO_L46P_4	AP15		
4	IO_L47N_4	AK16		
4	IO_L47P_4	AJ17		
4	IO_L48N_4	AU15		
4	IO_L48P_4	AT15		
4	IO_L49N_4	AM16		
4	IO_L49P_4	AL16		
4	IO_L50_4/No_Pair	AM17		
4	IO_L53_4/No_Pair	AL17		
4	IO_L54N_4	AP16		
4	IO_L54P_4	AN17		
4	IO_L55N_4	AR16		
4	IO_L55P_4	AR17		
4	IO_L56N_4	AH18		
4	IO_L56P_4	AG18		
4	IO_L57N_4	AU17		
4	IO_L57P_4/VREF_4	AT17		
4	IO_L58N_4	AM18		
4	IO_L58P_4	AL18		
4	IO_L59N_4	AK18		
4	IO_L59P_4	AJ18		
4	IO_L60N_4	AP18		
4	IO_L60P_4	AN18		
4	IO_L64N_4	AT18		
4	IO_L64P_4	AR18		
4	IO_L65N_4	AH19		
4	IO_L65P_4	AG19		
4	IO_L66N_4	AU18		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	M2	AJ29		
N/A	TCK	E8		
N/A	TDI	L30		
N/A	TDO	L10		
N/A	TMS	F9		
N/A	PWRDWN_B	AP9		
N/A	HSWAP_EN	E32		
N/A	RSVD	D8		
N/A	VBATT	L11		
N/A	DXP	L29		
N/A	DXN	F31		
N/A	AVCCAUXTX2	B35		
N/A	VTTXPAD2	B36		
N/A	TXNPAD2	A36		
N/A	TXPPAD2	A35		
N/A	GNDA2	C34		
N/A	RXPPAD2	A34		
N/A	RXNPAD2	A33		
N/A	VTRXPAD2	B34		
N/A	AVCCAUXRX2	B33		
N/A	AVCCAUXTX4	B31		
N/A	VTTXPAD4	B32		
N/A	TXNPAD4	A32		
N/A	TXPPAD4	A31		
N/A	GNDA4	C31		
N/A	RXPPAD4	A30		
N/A	RXNPAD4	A29		
N/A	VTRXPAD4	B30		
N/A	AVCCAUXRX4	B29		
N/A	AVCCAUXTX5	B27		
N/A	VTTXPAD5	B28		
N/A	TXNPAD5	A28		
N/A	TXPPAD5	A27		
N/A	GNDA5	C27		
N/A	RXPPAD5	A26		
N/A	RXNPAD5	A25		
N/A	VTRXPAD5	B26		
N/A	AVCCAUXRX5	B25		

FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS MIN.	NOM.	MAX.	NOTE
A		3.20	3.40	
A_1	0.40	0.50	0.60	
A_2			2.80	
D/E	40.00 BASIC			
D_1/E_1	38.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
bbb			0.25	
ddd			0.25	
eee			0.10	
M		39		2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAU-1 (DEPOPULATED)

Figure 8: **FF1517 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L35N_3		AH11		
3	IO_L35P_3		AH12		
3	IO_L34N_3		AH5		
3	IO_L34P_3		AH6		
3	IO_L33N_3/VREF_3		AH9		
3	IO_L33P_3		AH10		
3	IO_L32N_3		AJ11		
3	IO_L32P_3		AJ12		
3	IO_L31N_3		AJ1		
3	IO_L31P_3		AJ2		
3	IO_L30N_3		AJ5		
3	IO_L30P_3		AJ6		
3	IO_L29N_3		AJ9		
3	IO_L29P_3		AJ10		
3	IO_L28N_3		AJ7		
3	IO_L28P_3		AJ8		
3	IO_L27N_3/VREF_3		AK1		
3	IO_L27P_3		AK2		
3	IO_L26N_3		AK11		
3	IO_L26P_3		AK12		
3	IO_L25N_3		AK3		
3	IO_L25P_3		AK4		
3	IO_L24N_3		AK5		
3	IO_L24P_3		AK6		
3	IO_L23N_3		AK9		
3	IO_L23P_3		AK10		
3	IO_L22N_3		AK7		
3	IO_L22P_3		AK8		
3	IO_L21N_3/VREF_3		AL2		
3	IO_L21P_3		AL3		
3	IO_L20N_3		AL11		
3	IO_L20P_3		AL12		
3	IO_L19N_3		AL4		
3	IO_L19P_3		AL5		
3	IO_L18N_3		AL7		
3	IO_L18P_3		AL8		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	IO_L64N_5		AU24		
5	IO_L64P_5		AV24		
5	IO_L60N_5		AR24		
5	IO_L60P_5		AT24		
5	IO_L59N_5		AN24		
5	IO_L59P_5		AP24		
5	IO_L58N_5		AL24		
5	IO_L58P_5		AM24		
5	IO_L57N_5/VREF_5		AY26		
5	IO_L57P_5		AY25		
5	IO_L56N_5		AV25		
5	IO_L56P_5		AV26		
5	IO_L55N_5		AR25		
5	IO_L55P_5		AT25		
5	IO_L54N_5		AM25		
5	IO_L54P_5		AN25		
5	IO_L53_5/No_Pair		AW26		
5	IO_L50_5/No_Pair		AW27		
5	IO_L49N_5		AT26		
5	IO_L49P_5		AU26		
5	IO_L48N_5		AP26		
5	IO_L48P_5		AR26		
5	IO_L47N_5		AN26		
5	IO_L47P_5		AM26		
5	IO_L46N_5		AL26		
5	IO_L46P_5		AL25		
5	IO_L45N_5/VREF_5		AU27		
5	IO_L45P_5		AV27		
5	IO_L44N_5		AT27		
5	IO_L44P_5		AR27		
5	IO_L43N_5		AN27		
5	IO_L43P_5		AP27		
5	IO_L39N_5		AL27		
5	IO_L39P_5		AM27		
5	IO_L38N_5		AY28		
5	IO_L38P_5		AY29		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		V6		
N/A	GND		U25		
N/A	GND		U24		
N/A	GND		U23		
N/A	GND		U22		
N/A	GND		U21		
N/A	GND		U20		
N/A	GND		U19		
N/A	GND		U18		
N/A	GND		T42		
N/A	GND		T1		
N/A	GND		R39		
N/A	GND		R36		
N/A	GND		R7		
N/A	GND		R4		
N/A	GND		M42		
N/A	GND		M1		
N/A	GND		L22		
N/A	GND		L21		
N/A	GND		K39		
N/A	GND		K4		
N/A	GND		J34		
N/A	GND		J9		
N/A	GND		H42		
N/A	GND		H35		
N/A	GND		H22		
N/A	GND		H21		
N/A	GND		H8		
N/A	GND		H1		
N/A	GND		G36		
N/A	GND		G7		
N/A	GND		F37		
N/A	GND		F25		
N/A	GND		F18		
N/A	GND		F6		
N/A	GND		E38		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
3	IO_L67P_3	AU5	
3	IO_L66N_3	AU1	
3	IO_L66P_3	AU2	
3	IO_L65N_3	AJ9	
3	IO_L65P_3	AK8	
3	IO_L64N_3	AU8	
3	IO_L64P_3	AV8	
3	IO_L63N_3/VREF_3	AU7	
3	IO_L63P_3	AV7	
3	IO_L62N_3	AL8	
3	IO_L62P_3	AL9	
3	IO_L61N_3	AU3	
3	IO_L61P_3	AV2	
3	IO_L84N_3	AV6	
3	IO_L84P_3	AW5	
3	IO_L83N_3	AM8	
3	IO_L83P_3	AM9	
3	IO_L82N_3	AV4	
3	IO_L82P_3	AW4	
3	IO_L81N_3/VREF_3	AV3	
3	IO_L81P_3	AW3	
3	IO_L80N_3	AN9	
3	IO_L80P_3	AP8	
3	IO_L79N_3	AW1	
3	IO_L79P_3	AW2	
3	IO_L78N_3	AY7	
3	IO_L78P_3	AY8	
3	IO_L77N_3	AR8	
3	IO_L77P_3	AR9	
3	IO_L76N_3	AW7	
3	IO_L76P_3	AY6	
3	IO_L75N_3/VREF_3	AY3	
3	IO_L75P_3	AY4	
3	IO_L74N_3	AT9	
3	IO_L74P_3	AU9	
3	IO_L73N_3	AY5	
3	IO_L73P_3	BA5	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	IO_L66P_5	BA23	
5	IO_L65N_5	AL23	
5	IO_L65P_5	AL22	
5	IO_L64N_5	AT23	
5	IO_L64P_5	AU23	
5	IO_L60N_5	BA24	
5	IO_L60P_5	BB24	
5	IO_L59N_5	AN24	
5	IO_L59P_5	AP24	
5	IO_L58N_5	AW24	
5	IO_L58P_5	AW23	
5	IO_L57N_5/VREF_5	AU24	
5	IO_L57P_5	AV24	
5	IO_L56N_5	AN25	
5	IO_L56P_5	AP25	
5	IO_L55N_5	AR24	
5	IO_L55P_5	AR23	
5	IO_L54N_5	BA25	
5	IO_L54P_5	BB25	
5	IO_L53_5/No_Pair	AM25	
5	IO_L50_5/No_Pair	AM24	
5	IO_L49N_5	AY25	
5	IO_L49P_5	AY24	
5	IO_L48N_5	AU25	
5	IO_L48P_5	AV25	
5	IO_L47N_5	AM26	
5	IO_L47P_5	AN26	
5	IO_L46N_5	AT25	
5	IO_L46P_5	AT24	
5	IO_L18N_5/VREF_5	AY26	NC
5	IO_L18P_5	BA26	NC
5	IO_L16N_5	AT26	NC
5	IO_L16P_5	AU26	NC
5	IO_L12N_5	AL26	NC
5	IO_L12P_5	AL25	NC
5	IO_L11N_5	BA27	NC
5	IO_L11P_5	BB27	NC

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AF1	
N/A	GND	AC1	
N/A	GND	Y1	
N/A	GND	U1	
N/A	GND	N1	
N/A	GND	J1	
N/A	GND	E1	

Notes:
1. See Table 4 for an explanation of the signals available on this pin.